

INTERNATIONAL STANDARD



**Optical circuit boards – Basic test and measurement procedures –
Part 2: General guidance for definition of measurement conditions for optical
characteristics of optical circuit boards**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

OPTICAL CIRCUIT BOARDS – BASIC TEST AND MEASUREMENT PROCEDURES –

Part 2: General guidance for definition of measurement conditions for optical characteristics of optical circuit boards

FOREWORD

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International Standard IEC 62496-2 has been prepared by IEC technical committee 86: Fibre optics.

The text of this document is based on the following documents:

CDV	Report on voting
86/509/CDV	86/515/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62496 series, published under the general title *Optical circuit boards – Basic test and measurement procedures*, can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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INTRODUCTION

Bandwidth densities in modern data communication systems are driven by interconnect speeds and scalable input/output (I/O) and will continue to increase over the coming years, thereby severely impacting cost and performance in future data communication systems, bringing increased demands in terms of signal integrity and power consumption.

The projected increase in capacity, processing power and bandwidth density in future information communication systems will need to be addressed by the migration of embedded optical interconnects into system enclosures. In particular, this would necessitate the deployment of optical circuit board technologies on some or all key system cards, such as the backplane, motherboard and peripheral circuit boards.

Many varieties of optical circuit board technology exist today, which differ strongly from each other in terms of their intrinsic waveguide technology. As shown in Figure 1, these varieties include, but are not limited to: a) fibre-optic laminate, b) polymer waveguides and c) planar glass waveguides. Annex A provides a detailed overview of the state of the art of such optical interconnect technologies.

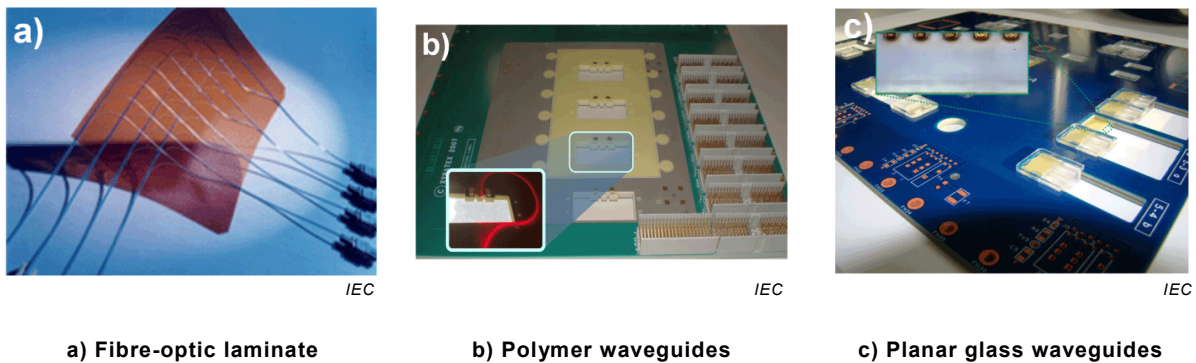


Figure 1 – Optical circuit board varieties

One important prerequisite to the commercial adoption of optical circuit boards is a reliable test and measurement definition system that is agnostic to the type of waveguide system under test and, therefore, can be applied to different optical circuit board technologies as well as being adaptable to future variants. A serious and common problem with the measurement of optical waveguide systems has been lack of proper definition of the measurement conditions for a given test regime, and consequently strong inconsistencies ensue in the results of measurements by different parties on the same test sample. To date, no methodology has been established to ensure that test and measurement conditions for such optical waveguide systems are properly identified.

This document specifies a method of capturing sufficient information about the measurement conditions for a given optical circuit board to ensure consistency of measurement results within an acceptable margin.

Given the substantial variety in properties and requirements for different optical circuit board types, some test environments and conditions are more appropriate than others for a given optical circuit board. It is, therefore, crucial that this measurement identification standard encompass a comprehensive range of test and measurement scenarios for all known types of optical circuit boards and their waveguide systems, while also being sufficiently adaptable and extendable to accommodate future waveguide technologies. In addition, a degree of customisation is possible to account for arbitrary test parameters.

OPTICAL CIRCUIT BOARDS – BASIC TEST AND MEASUREMENT PROCEDURES –

Part 2: General guidance for definition of measurement conditions for optical characteristics of optical circuit boards

1 Scope

This part of IEC 62496 specifies a method of defining the conditions for measurements of optical characteristics of optical circuit boards. The method comprises the use of code reference look-up tables to identify different critical aspects of the measurement environment. The values extracted from the tables are used to construct a measurement identification code, which, in itself, captures sufficient information about the measurement conditions, so as to ensure consistency of independently measured results within an acceptable margin. Recommended measurement conditions are specified to minimise further variation in independently measured results.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61300-1, *Fibre optic interconnecting devices and passive components – Basic test and measurement procedures – Part 1: General and guidance*

IEC 61300-3-53, *Fibre optic interconnecting devices and passive components – Basic test and measurement procedures – Part 3-53: Examinations and measurements – Encircled angular flux (EAF) measurement method based on two-dimensional far field data from step index multimode waveguide (including fibre)*

IEC 62614, *Fibre optics – Launch condition requirements for measuring multimode attenuation*

IEC 62496-2-1:2011, *Optical circuit boards – Part 2-1: Measurements – Optical attenuation and isolation*